Amendments to the Specification:

At page 3, please add the following new paragraph after paragraph [0021]:

[0021a] FIG. 7 is an exploded view of the various elements to be stacked in the order in which they connect to one side of the printed circuit card using a chock.

Page 7, paragraph [0051), please amend the following paragraphs:

[0051] During the mounting, or removal followed by a remounting, of this second integrated circuit 4B, the tool 35, i.e., a package tool 35, is placed, for example, on a horizontal support 50, the shafts 29-30 being directed upward. The printed circuit card 2 is placed on this package tool 35 in order to insert the assembly A created into the package tool 35, the axes of the standoffs 16-19 coinciding with the axes of the shafts 29-30 of the package tool 35.

[0052] Preferably, the package tool 35 is attached to the printed circuit card for better handling. The method of attachment is arbitrary.

[0053] The springs 31-32 of the package tool 35 come into contact with the heads of the screws (20A-23A) of the assembly A. Inside the package tool 35, each spring 31-32 exerts a force that compensates for the weight of this assembly, thereby preventing any translational movement of the standoffs 16-19 perpendicular to the printed circuit card 2.

Page 8, please amend paragraph [0061]:

[0061] A preliminary step consists of inserting, through the holes 11-14 provided for this purpose in the printed circuit 2, and on the opposite side of the

printed circuit card onto which the integrated circuit 4A is to be mounted, a center chock 70, as shown in FIG. 7. This center chock 70 is equivalent in size to a plate 24A or 24B, but with a thickness representative of the thickness of an assembly. The springs are placed around the standoffs and the center chock 70 is pressed against the printed circuit card 2 by means of screws 20B-23B.

Page 9, please amend paragraph [0081]:

[0081] Next, the assembly A is placed inside the package tool 35 so that the springs 31-32 of the ~~containing~~ package tool 35 come into contact with the heads of the screws of the assembly A.

At page 10, please amend paragraph [0083]:

[0083] The next step consists of removing the center chock 70 inserted in step E1. During the removal of the center chock 70, the springs of the package tool 35 exert a force that compensates for the weight of the assembly A inside the package tool 35 and thus prevents the standoffs and the assembly A from moving in a direction perpendicular to the plane of the printed circuit card.

At page 10, please amend paragraph [0088]:

[0088] The assembly A is placed inside the package tool 35 so that the springs 31, 32 of the latter come into contact with the heads of the screws of the assembly A.

At page 10, please amend paragraph [0090]:

[0090] The screws 20B-23B are then unscrewed so as to release the pressure of the respective springs 25B-28B. At the end of the operation, the springs 31, 32 of

the package exert a force that compensates for the weight of the assembly A inside the package tool 35 and thus prevents the standoffs and the assembly A from moving in a direction perpendicular to the plane of the printed circuit card.